

# Update on IHEP RD50 activities

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On behalf of IHEP RD50 Group



中国科学院高能物理研究所

# Outline

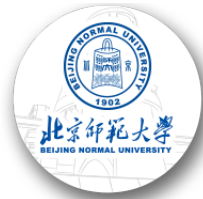
- LGAD Sensor Development
- Proton Irradiation at CIAE
- TCT and Beta source test
- TCAD irradiation modeling
- TRACS development

# LGAD Sensor Development Status

Zhijun Liang, et al.

# LGAD Development in China

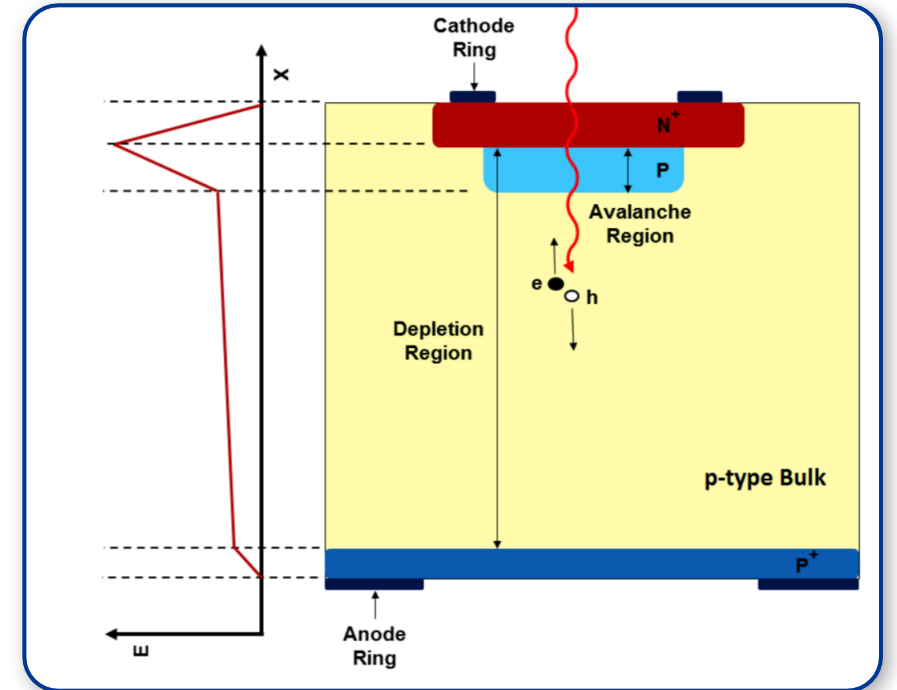
- LGAD sensor with epitaxial layer wafer
  - Collaboration with Beijing Normal University Novel Device Laboratory (NDL)
  - Lower resistivity in epitaxial layer ( $300 \Omega\cdot\text{cm}$ )



- “High resistance wafer” + “low resistance” bonded wafer
  - Collaboration with Tsinghua University
  - High resistance wafer ( $> 10\text{k} \Omega\cdot\text{cm}$ )



清华大学  
Tsinghua University

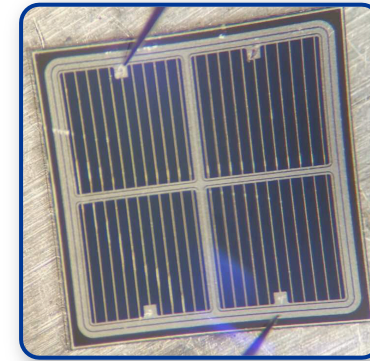
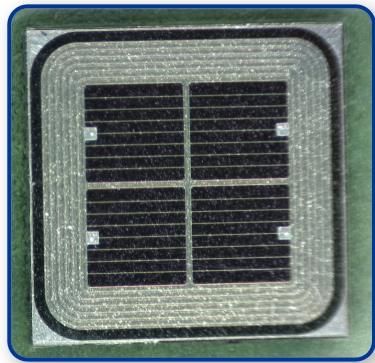




# IHEP-NDL Sensor Design

- 6 guard ring: BV170, BV60 (floating, no metal contact)

- 2 guard ring: **Type 9#, 10#** *New!*  
(with metal contact, can be grounded)
- Higher breakdown voltage (VBD) with new guard ring design

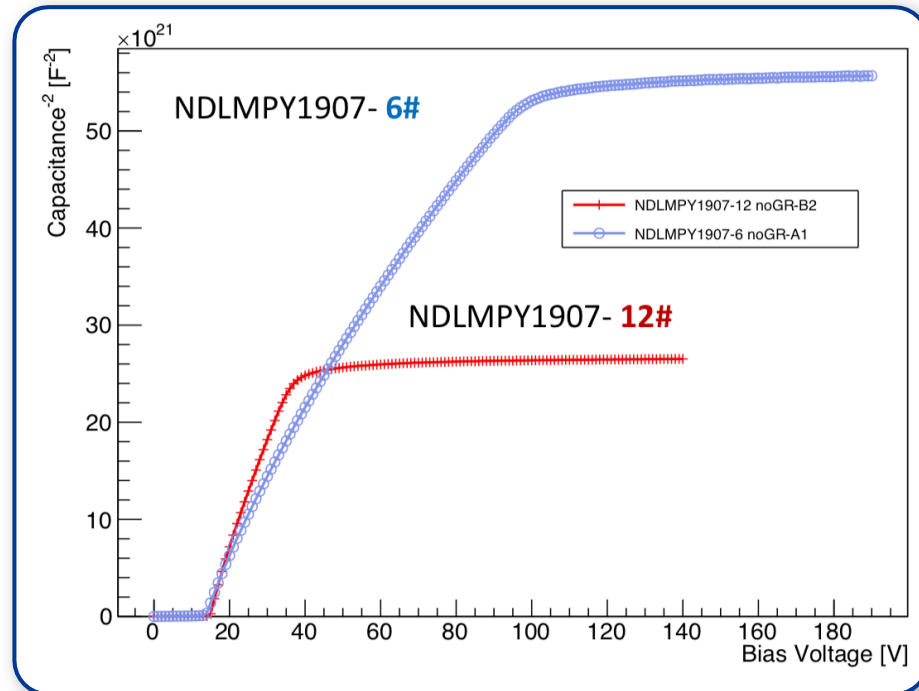
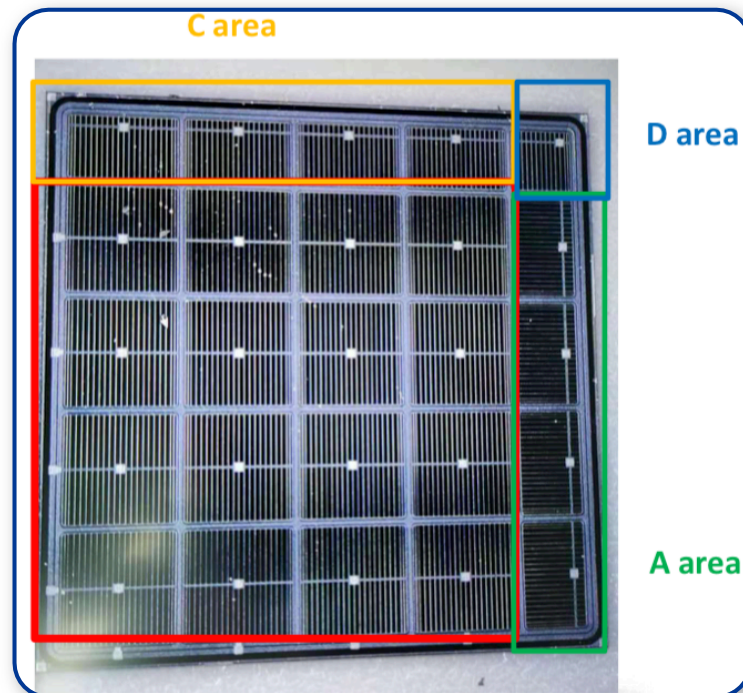


	VBD	V <sub>Depleted</sub>	Layout	Wafer	Gain
Type 13# (BV170)	~165V	~100V	6GR	100Ω.cm	40
Type 12#(BV60)	~95V	~40V	6GR	300Ω.cm	40
<b>Type 10#</b>	~300V	~40V	2GR	300Ω.cm	80
<b>Type 9#</b>	~250V	~40V	2GR	300Ω.cm	80

# NDL 5x5 sensors

- Two types of NDL 5x5 sensors fabricated in September 2019

	VBD	V <sub>Depleted</sub>	Layout	Epi layer(33μm) resistance	Gain
NDL 5x5 6#	~250V	~120V	2 guard ring	100Ω.cm	10~20
NDL 5x5 12#	~235V	35V	2 guard ring	300Ω.cm	10~20

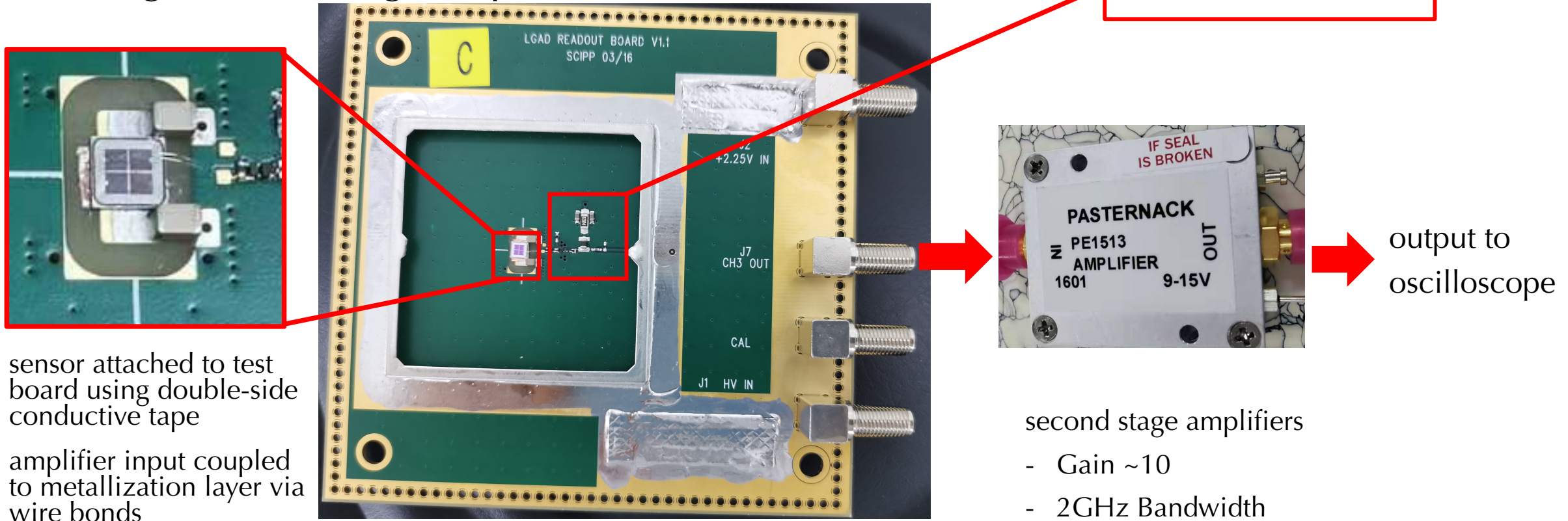


# Laser and Beta source test

Yuzhen Yang, et al.

# Laser and Beta source test: readout board

- LGAD readout boards with trans-impedance first stage amplifier (designed by UCSC)
- Voltage second stage amplifiers: PE1513

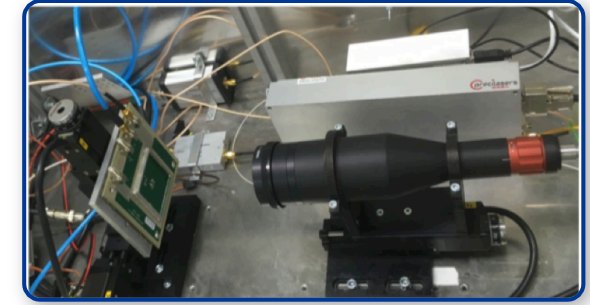


- sensor attached to test board using double-side conductive tape
- amplifier input coupled to metallization layer via wire bonds

# Laser test for NDL LGAD Sensor

- Time resolution of LGAD sensor

$$\sigma_t^2 = \sigma_{TDC}^2 + \sigma_{Time\ Walk}^2 + \sigma_{Landau\ Noise}^2 + \sigma_{Signal\ distortion}^2 + \sigma_{Jitter}^2$$

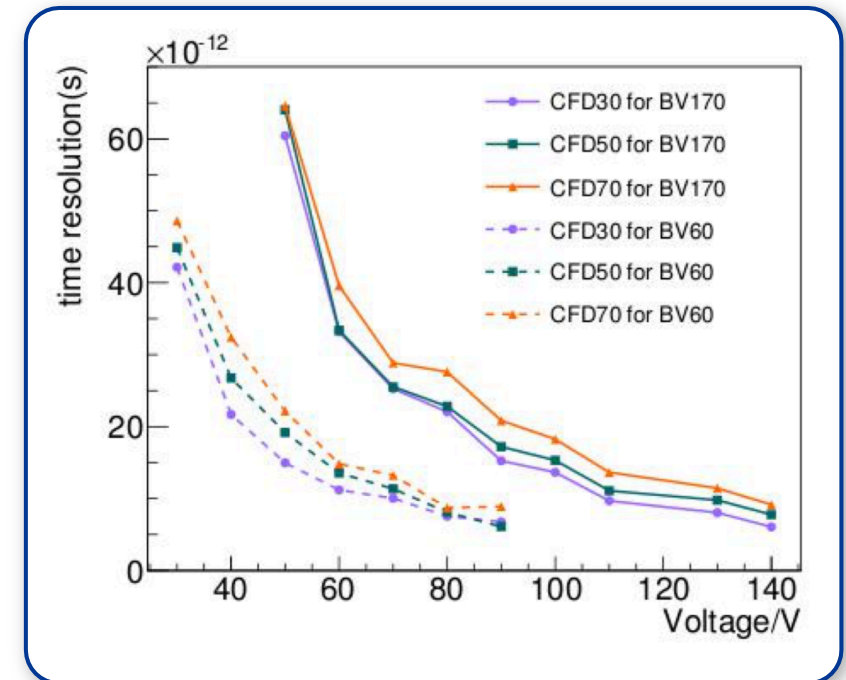


- Time resolution test system using pico-second laser

- Laser pulse width: 7ps
- Wavelength: 1064nm
- Frequency: 20MHz

- Evaluate the jitter contribution

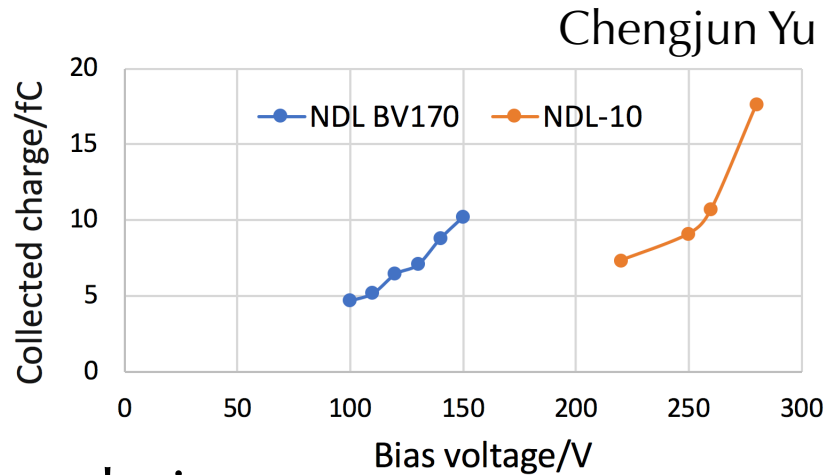
- Less than 10ps at room temperature
- Laser power larger than MIP
- Next: irradiated sensor at low temperature





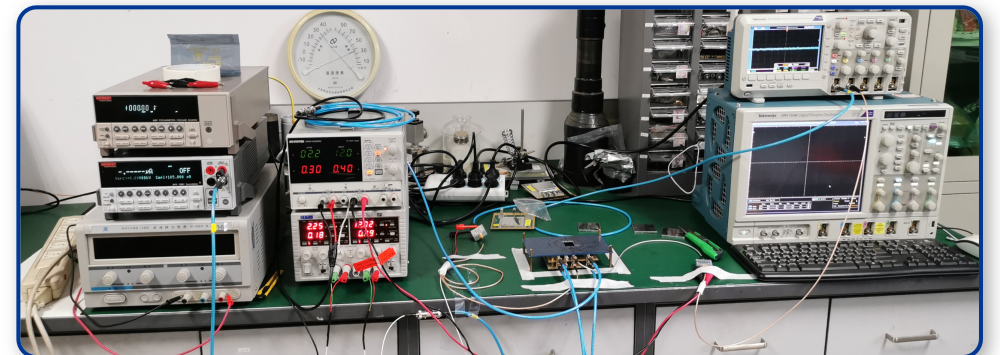
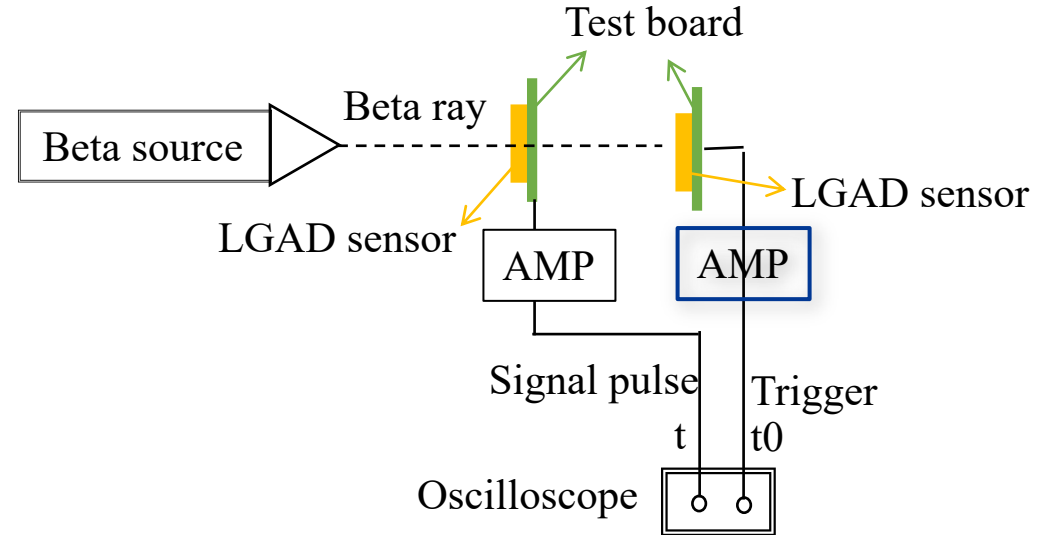
# Beta source test for NDL sensor

- Collected charge



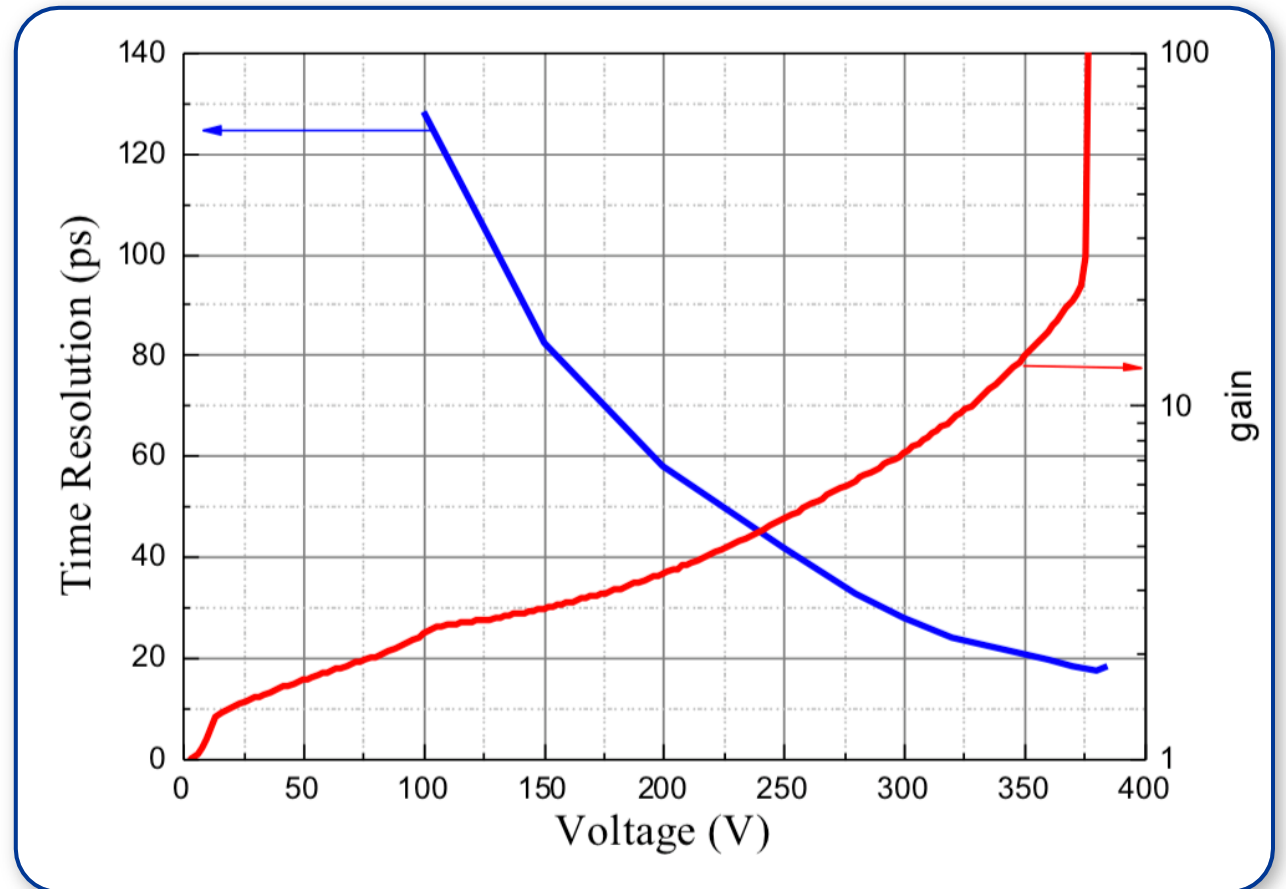
- Time resolution

- Using two LGAD sensor coincidence as trigger
- commission on the way
- Next: test time resolution at room and low temperature



# Time resolution vs. gain in 5x5 NDL LGAD

- Pico-second laser measurement
  - The power of the laser is reduced to simulate MIP
  - Jitter term can reach 20ps in this laser tests
    - Note: Landau term can not be evaluated in laser test



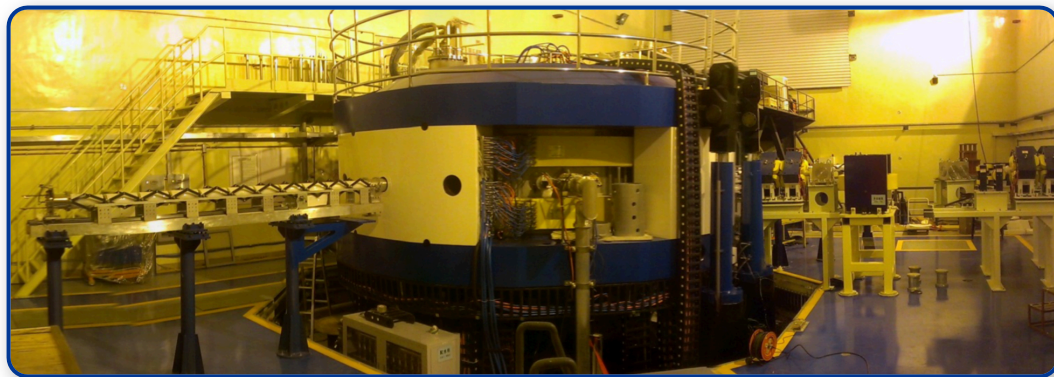
# CIAE Irradiation Campaign

Yuhang Tan, et al.

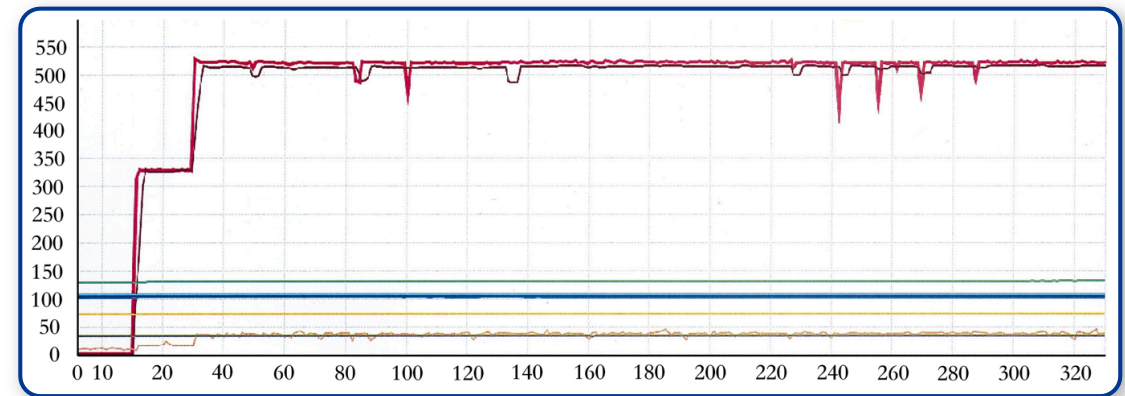


# Proton irradiation facilities in China

- China Institute of Atomic Energy (CIAE) in Beijing
- 100 MeV proton synchrotron
  - Beam energy: 20 –100 MeV
  - Beam current: 1 pA – 200 μA
  - Experiment terminal: 5



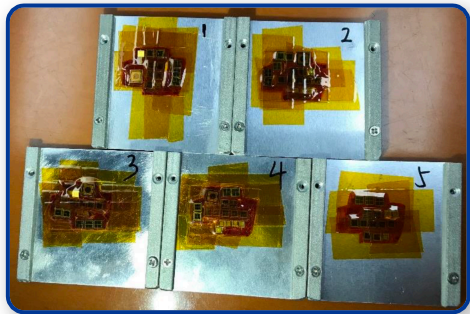
Beam current (μA)



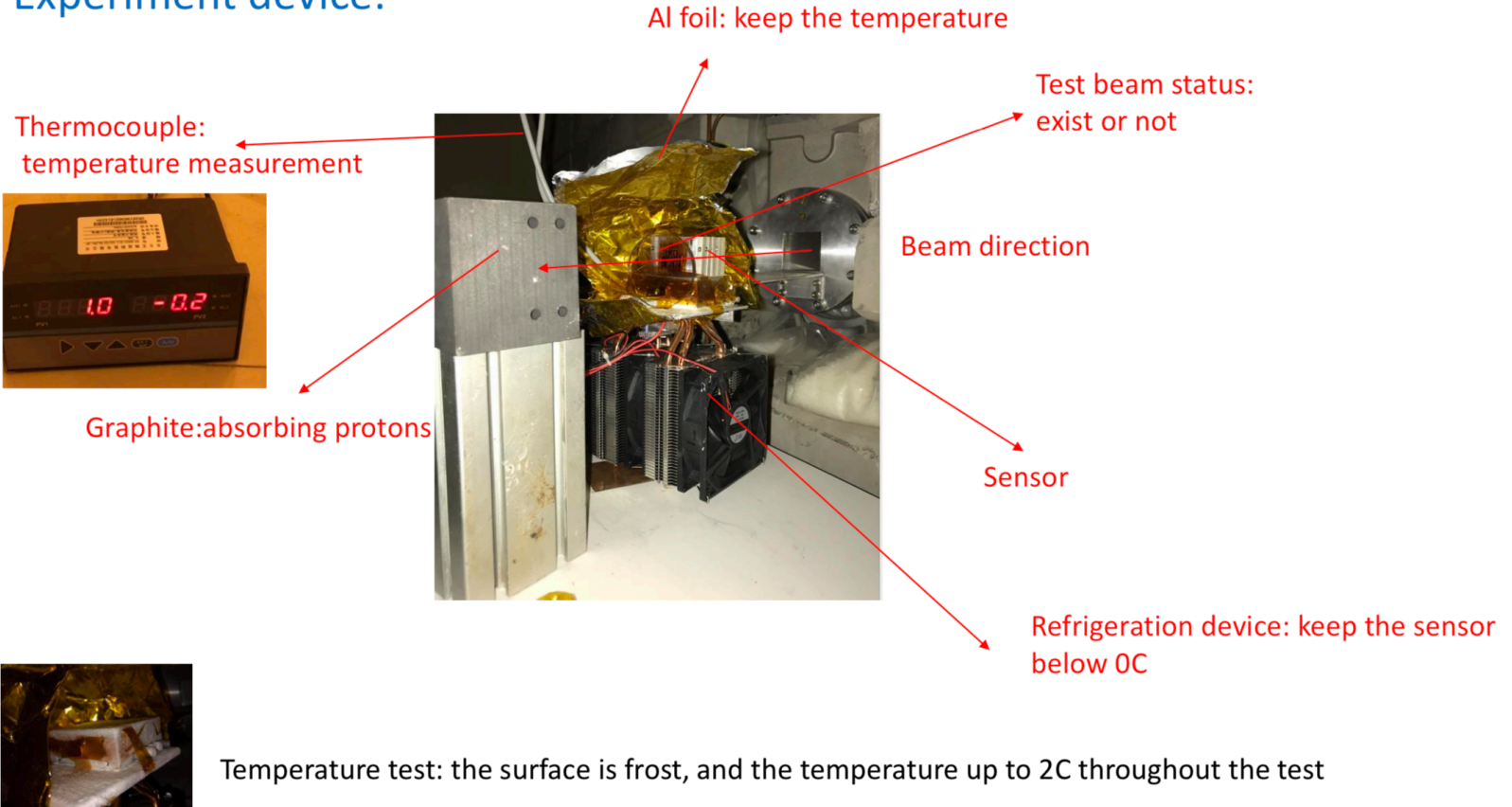
Time (s)

# CIAE irradiation campaign

- Irradiation was carried out on July 9
- 5 fluence points were chosen:  $7E14$ ,  $1E15$ ,  $2E15$ ,  $3E15$ ,  $4.5E15$
- 18 HPK, 4 CNM, 55 IHEP-NDL
- Beam current: 100nA (~1-2%)
- Beam area: 2.5cm X 2.5cm
- Temperature: below 0C

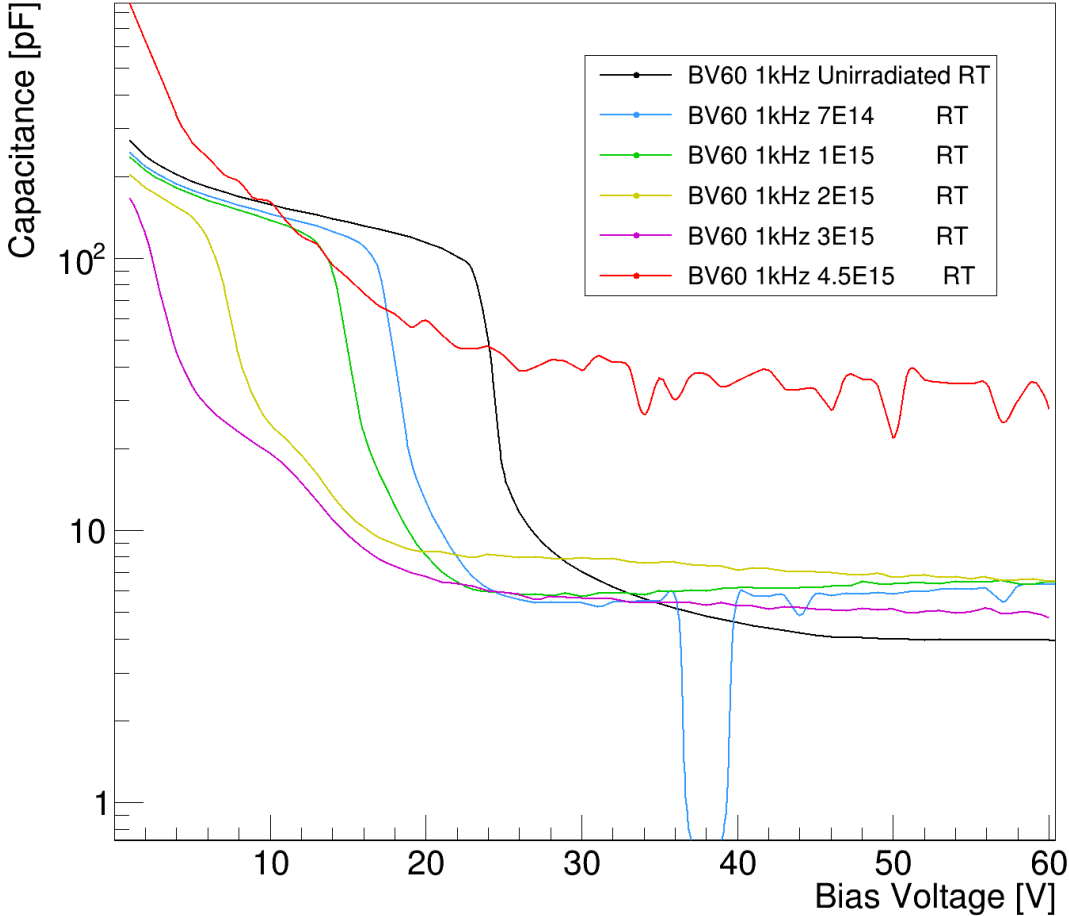
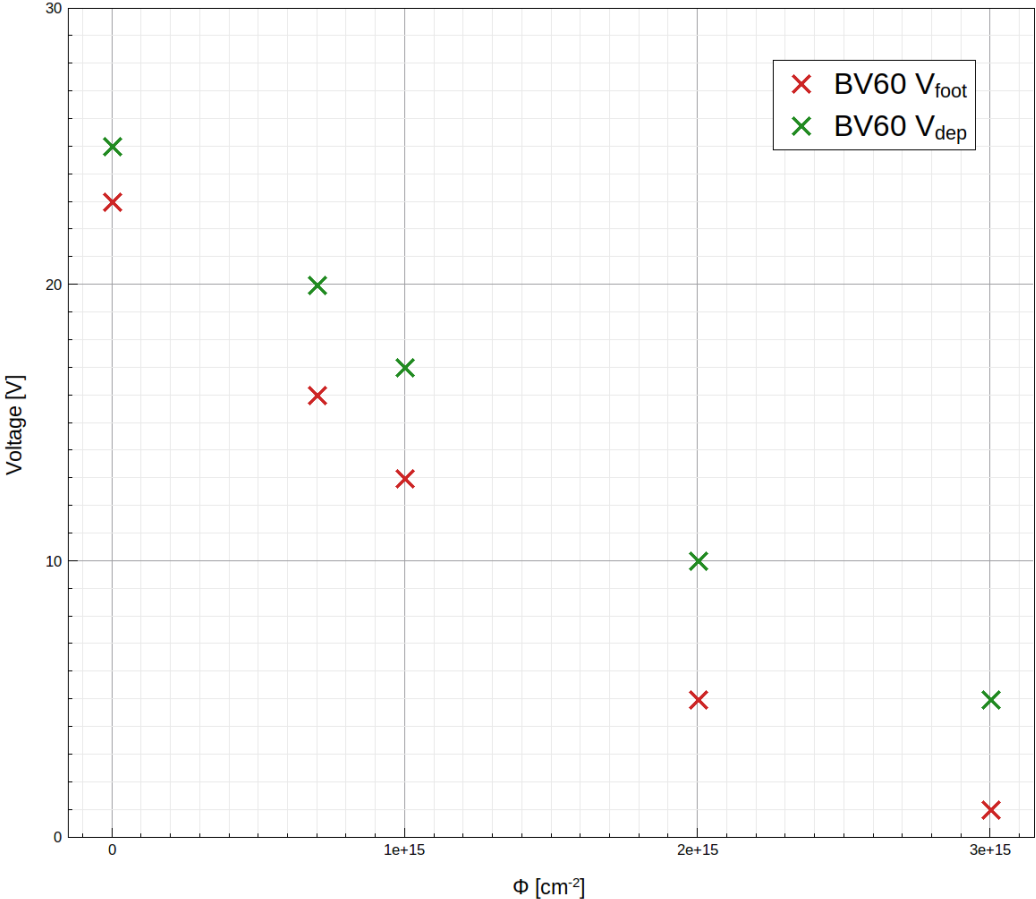


## Experiment device:

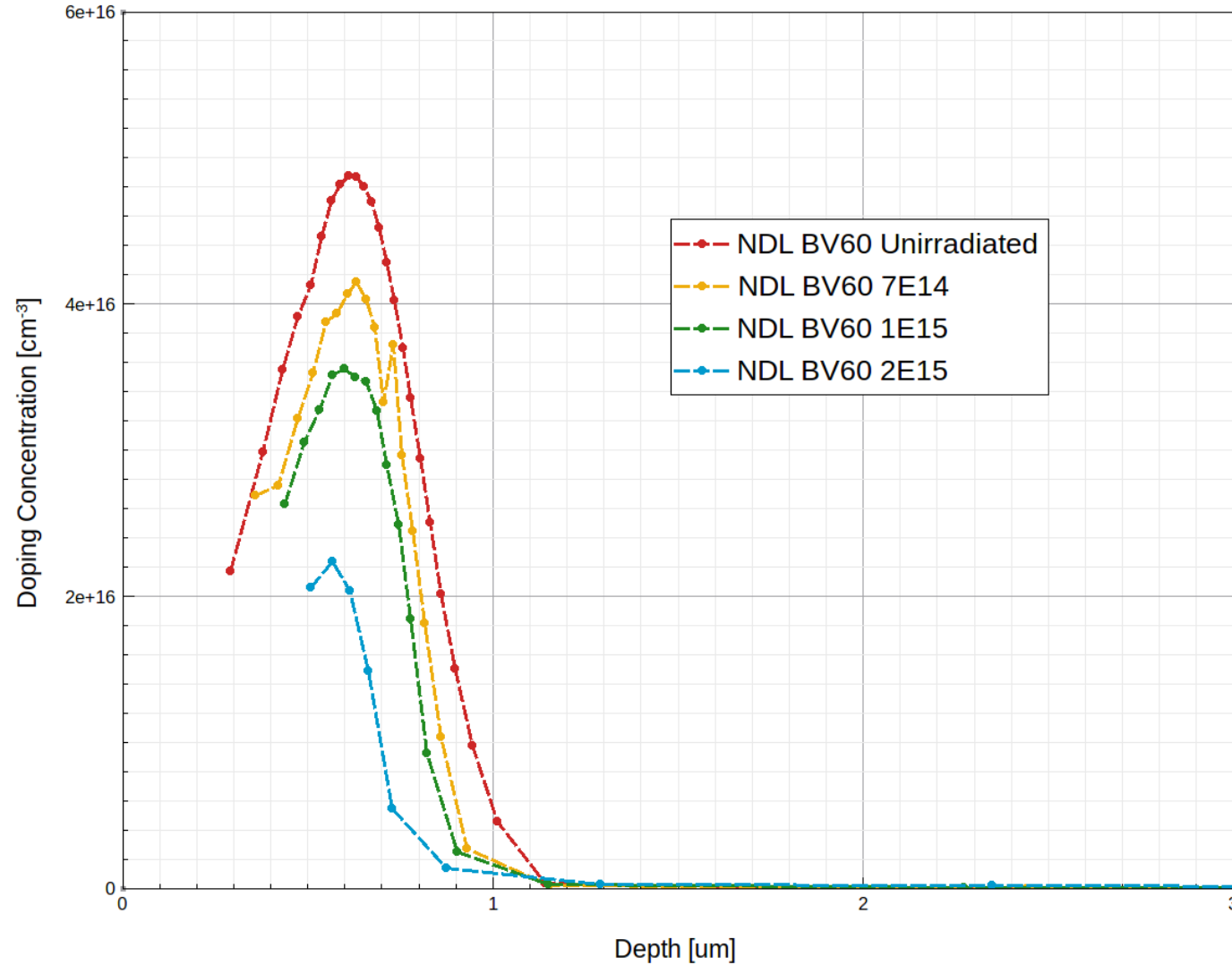


# First Results of CIAE irradiation: NDL sensors

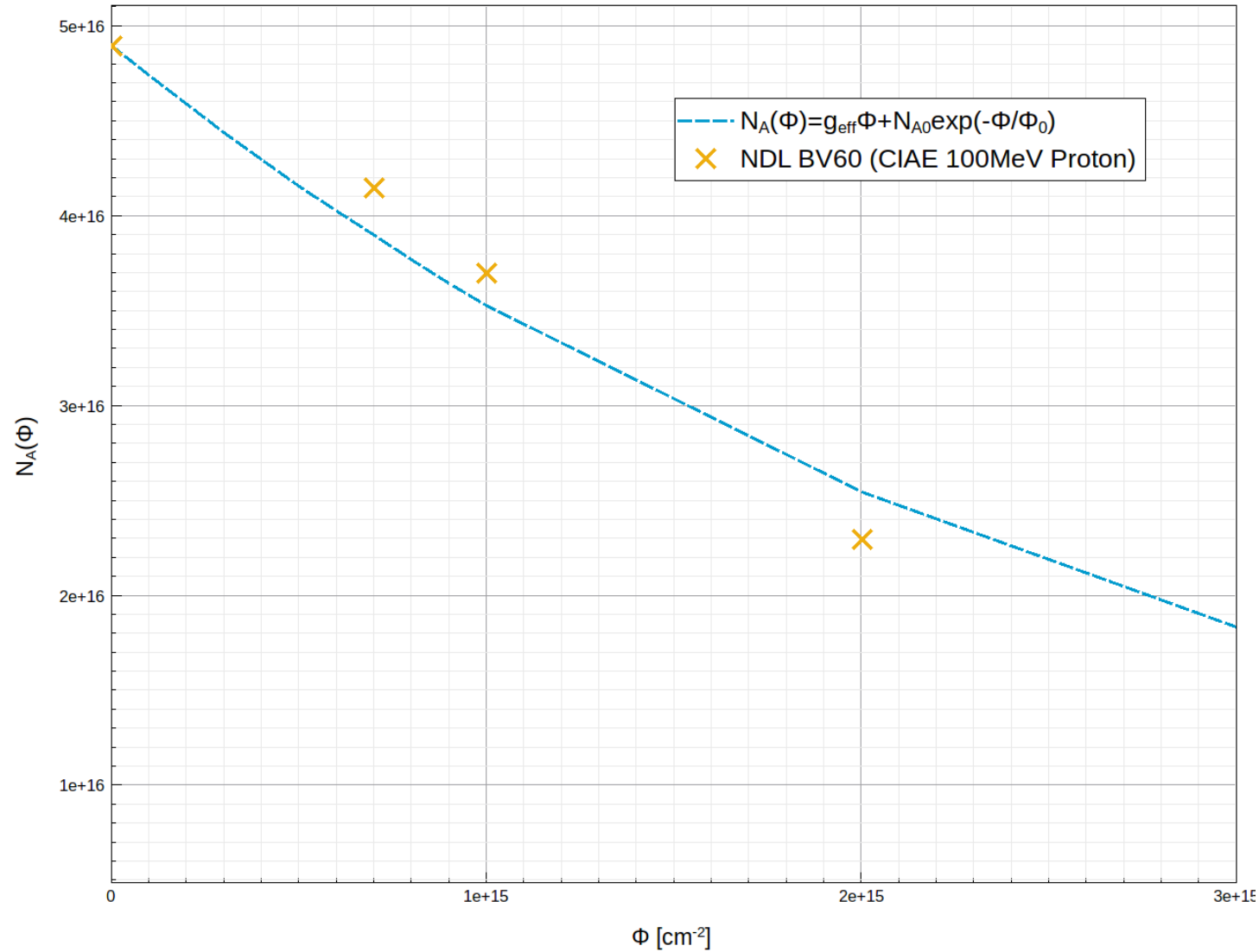
- Depleted voltage and foot voltage vs. fluence



# Doping profile vs. Fluence



# Acceptor removal effect



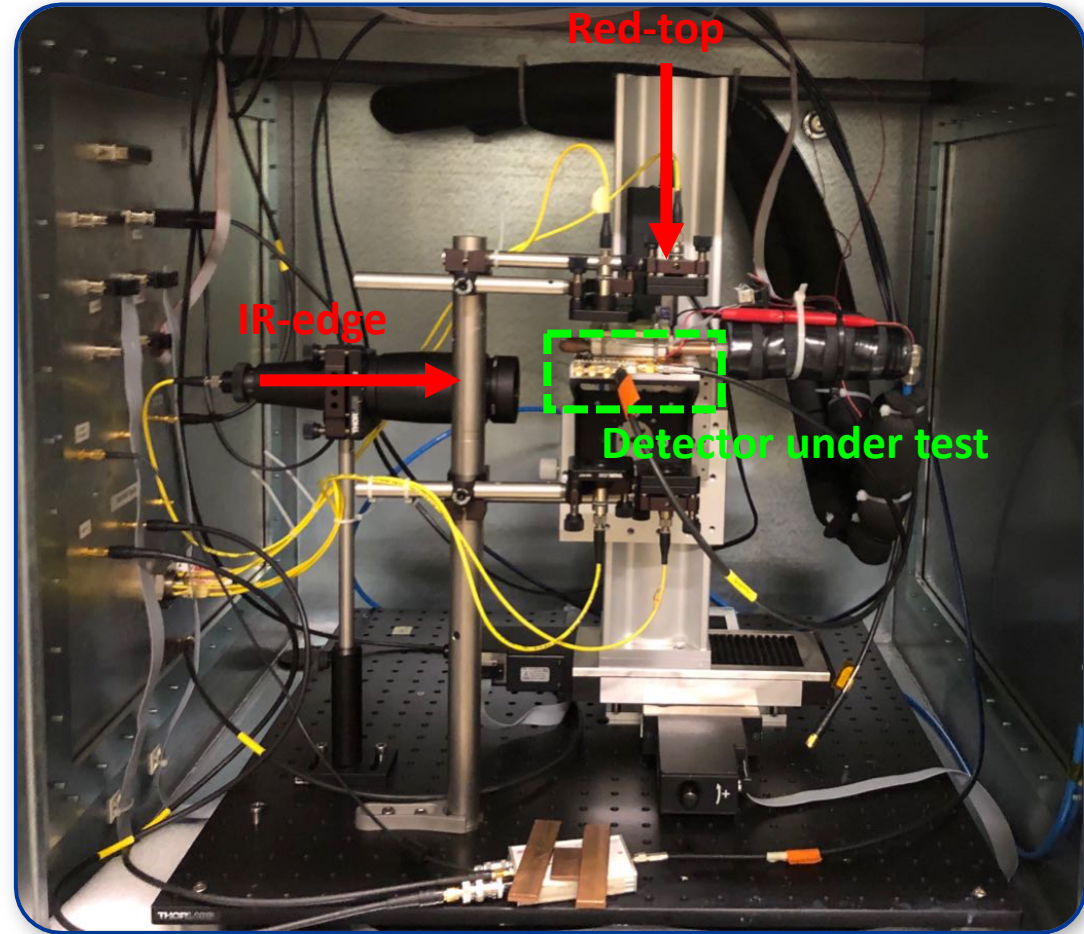
# TCT Measurement

Suyu Xiao, et. al



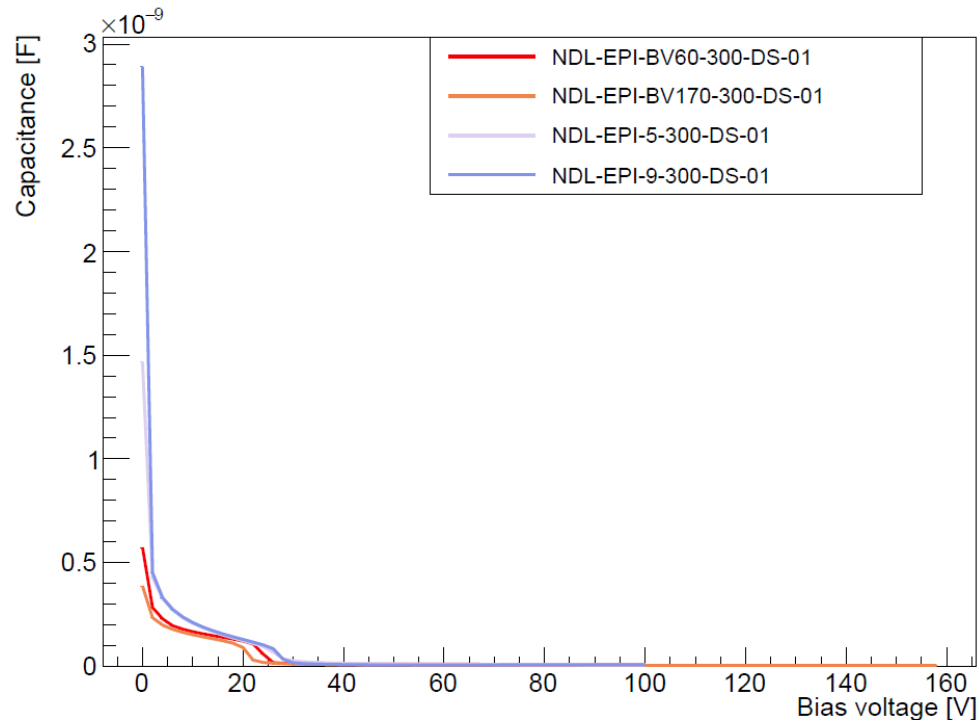
# TCT Setup at CERN

- 664nm for Red laser
- 1064nm for IR laser
- $\sim 4\mu\text{m}$  spatial resolution

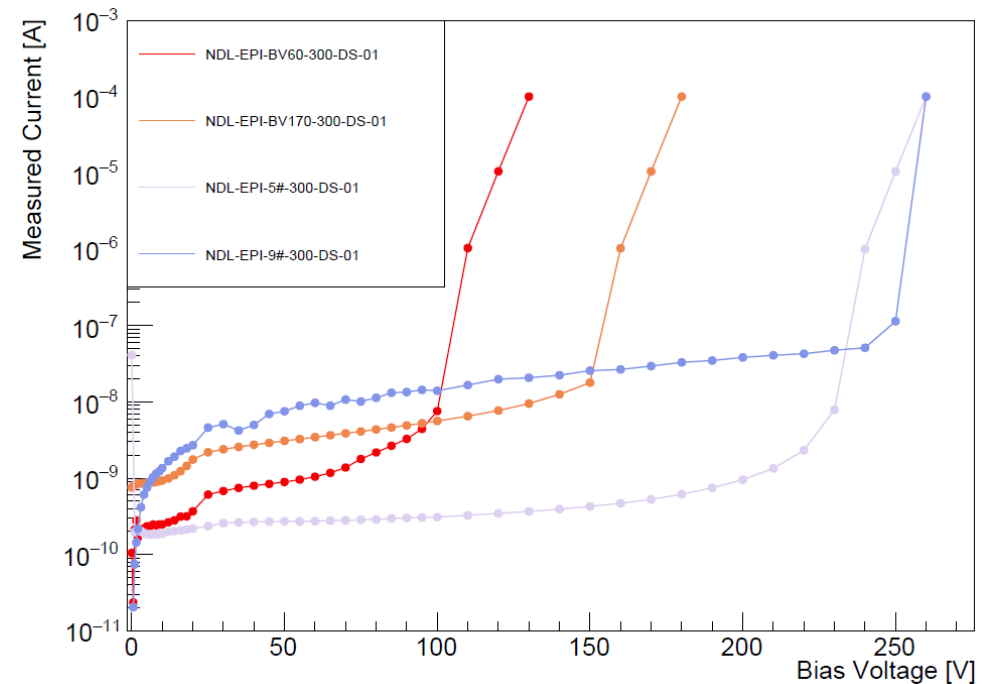


# CV and IV measurement of NDL BV170

CV curve of BV170



IV curve of BV170

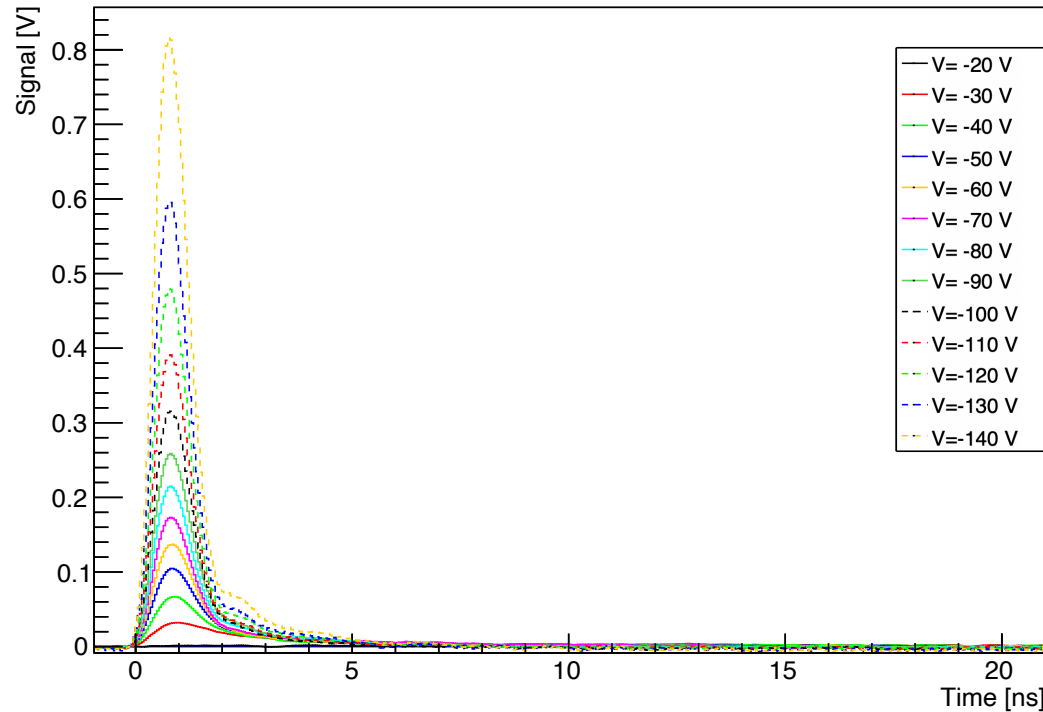


- BV170 depleted at 105V, breakdown at 155V.

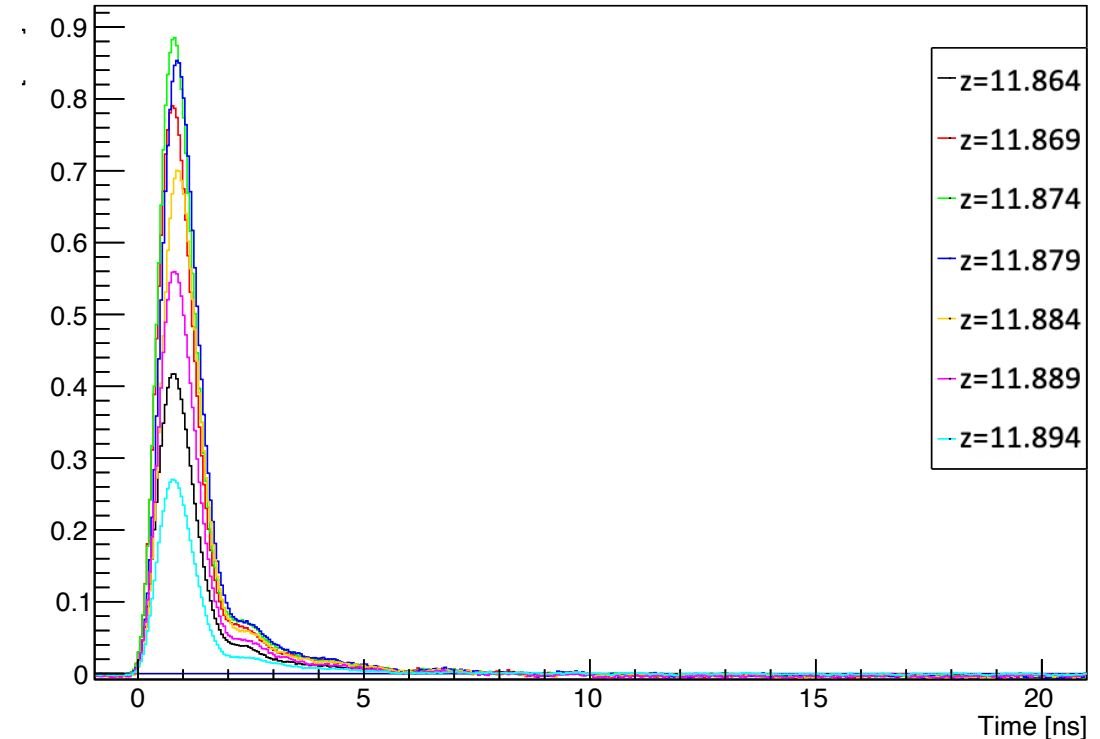


# NDL BV170-05 IR-edge 2.65mm

- Waveform at different  $V_{\text{bias}}$



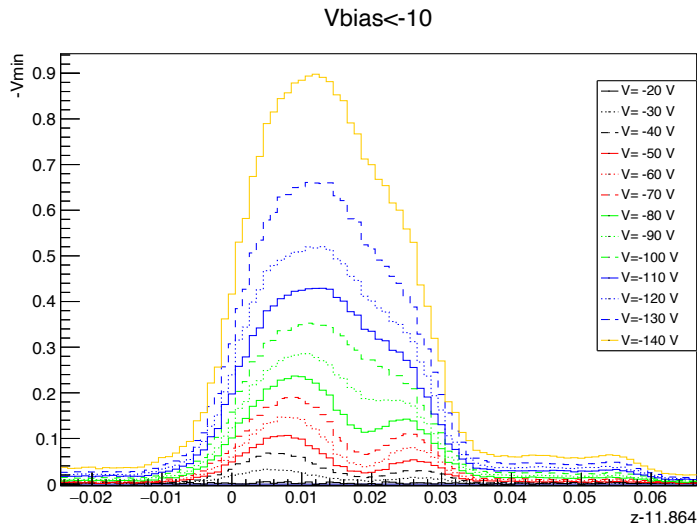
- Current at different depth



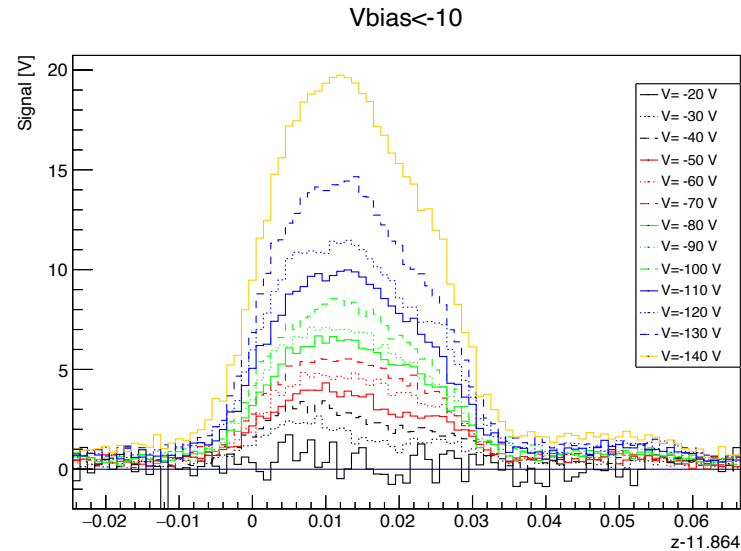
- Do voltage scan on BV170 from 20V to 140V. Obvious signal appears from 30V.
- 7 depths are chosen to compare current (50 μm a point, 300 μm in total, 7 point). ~100 μm from the top achieves the maximum current, then decreasing slowly.

# NDL BV170-05 IR-edge 2.65mm

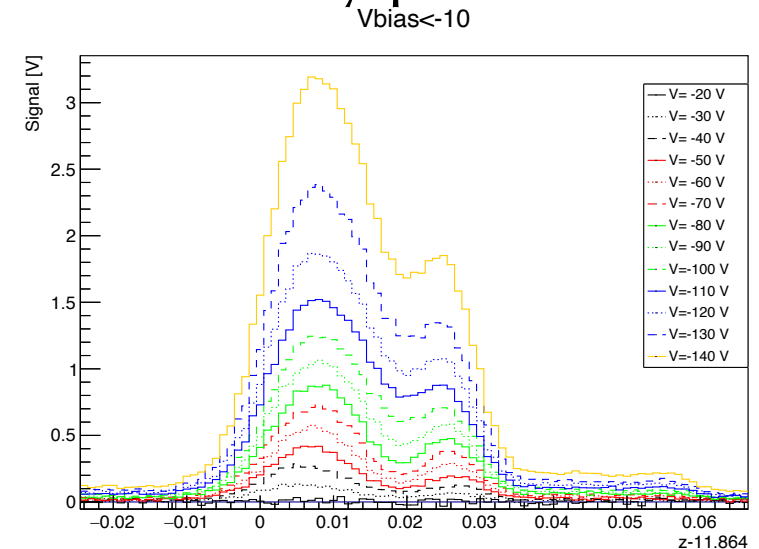
- Pulse Height at different depth



- Charge collection in 20ns



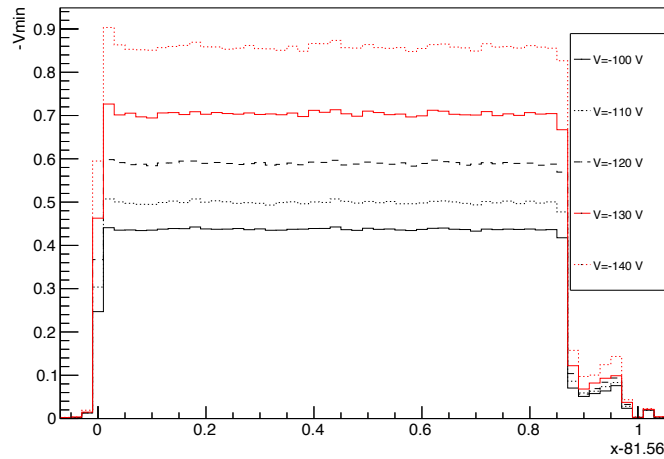
- Velocity profile



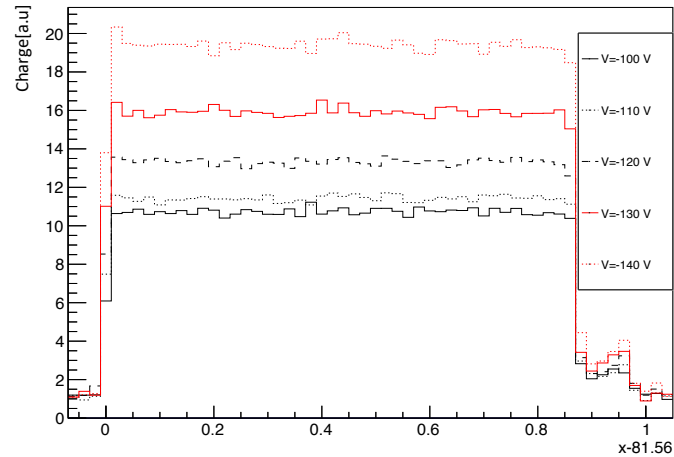
- A second peak in velocity is shown for LGAD near the bottom before irradiation, caused by the electric field from the diffusion of holes from the  $p+$  region into the  $p$  bulk region.

# NDL BV170-05 Red-top 2.95mm

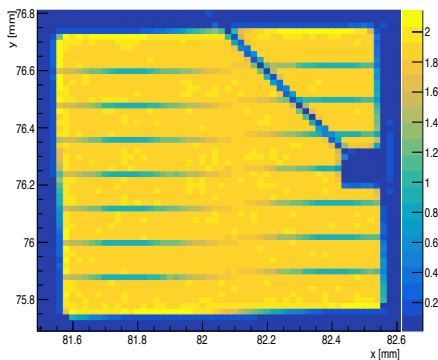
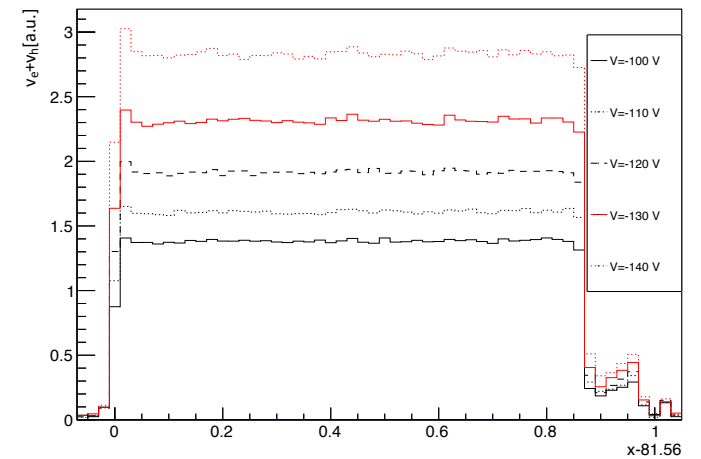
- Pulse Height at different depth



- Charge collection in 20ns



- Velocity profile



- Good spatial uniformity can be seen from the top scan.

# TCT Measurement Plan

- Irradiated samples with different fluences are needed.  
Following 3 fluences will be irradiated with neutron at Ljubljana.
  - $1e14$
  - $1e15$
  - $2.5e15$

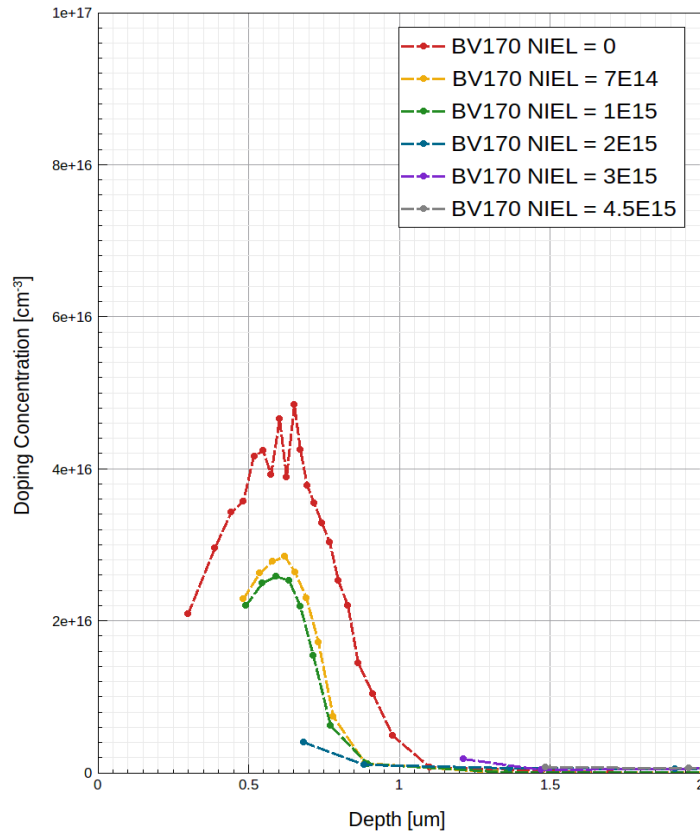
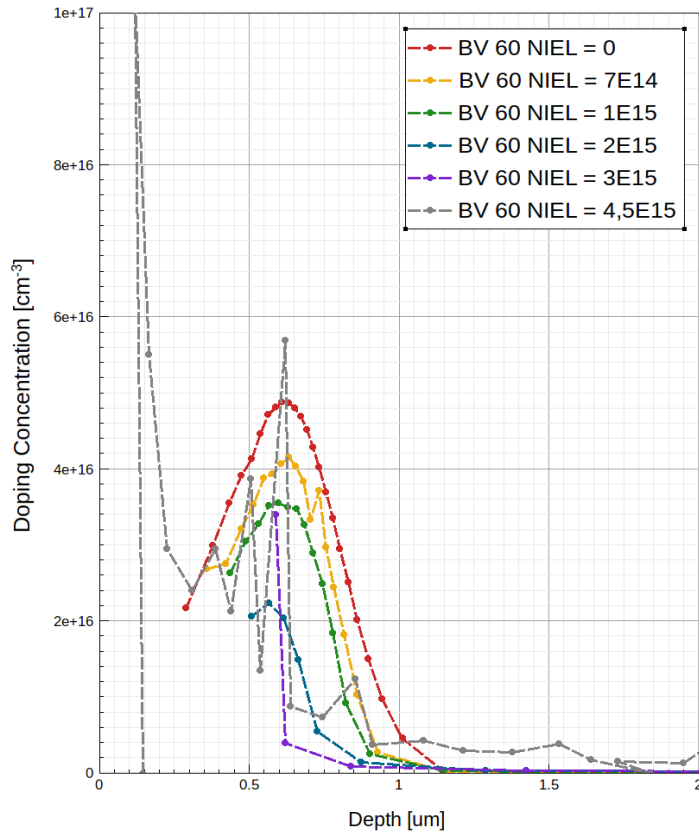
# Irradiation Modeling with TCAD

Tao Yang

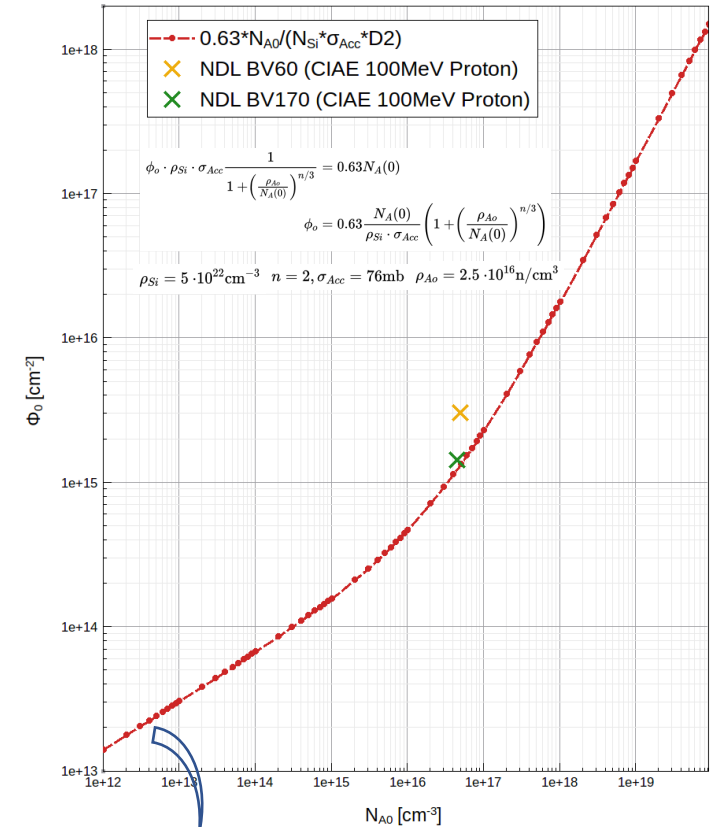
# Acceptor Removal Measurements

- Doping profile extracted from CV measurements
  - Temperature: 22 °C
  - Frequency: 1kHz

the number of initial acceptor atoms deactivated by radiation is given by the product of the fluence  $\phi_o$



Doping profile extracted from CV for BV60(left) and BV170(right) in various fluence.



Radiation resistance

# Acceptor Removal Simulation in TCAD

- Effective acceptor

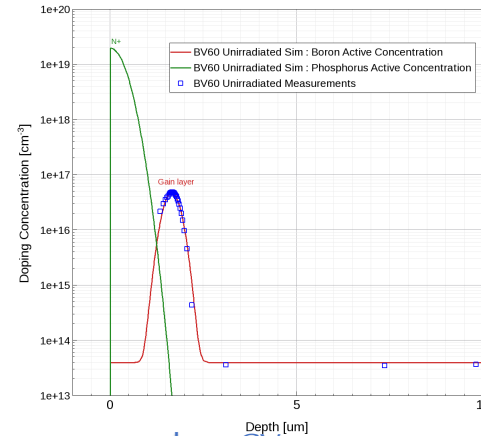
$$N_A(\phi) = g_{eff}\phi + N_A(0)e^{-c\phi}$$

$\rho_A(0)(\rho_A(\phi))$  the initial (after a fluence  $\phi$ ) acceptor density [ $\text{cm}^{-3}$ ]

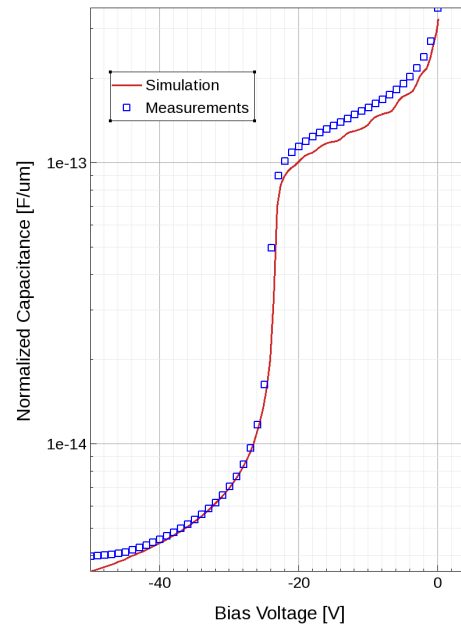
$$g_{eff} = 0.02 [\text{cm}^{-1}]$$

$\phi_o = 1/c$  is the fluence needed to reduce the initial doping density to 1/e of its initial value.

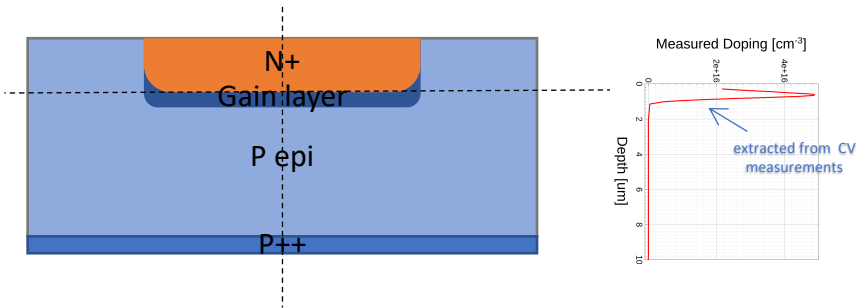
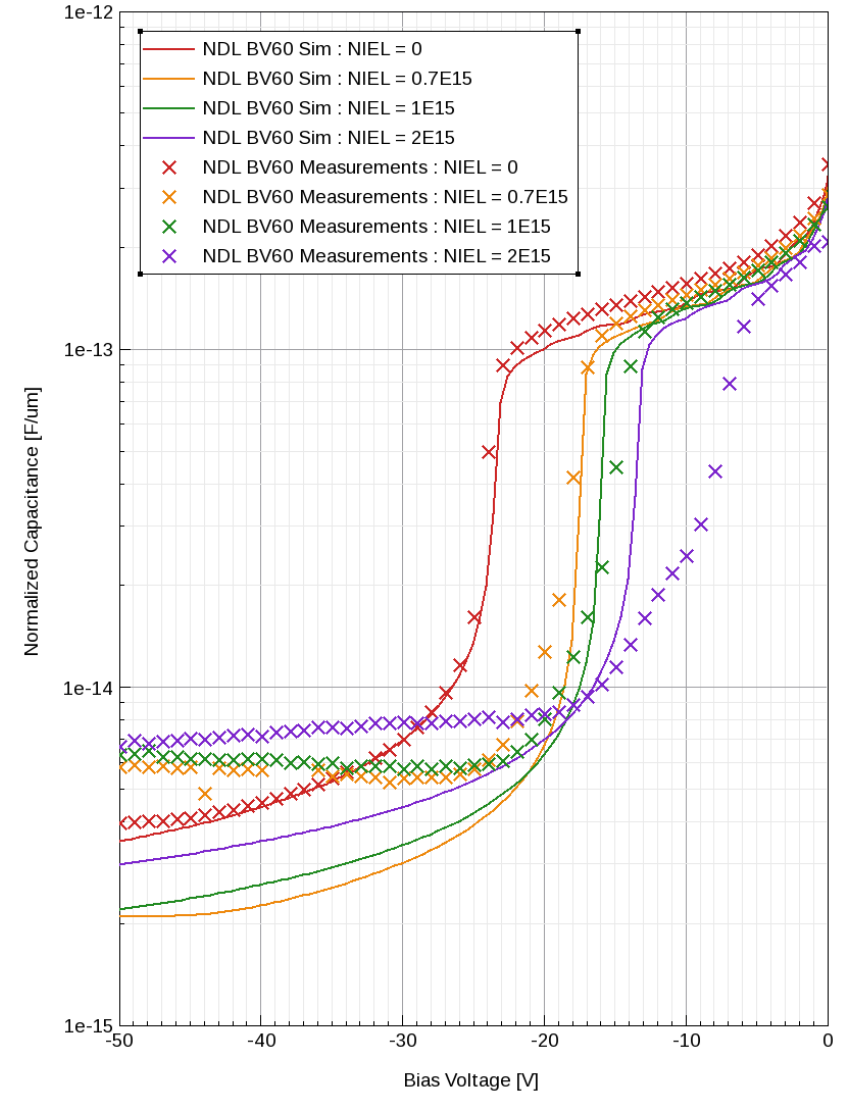
doping depth calibration



reproduce CV



couple with acceptor removal model



# Next for TCAD simulation on LGAD:

- Couple with Deep energy levels(DLs) to reproduce radiation effect on IV, CCE and gain.
- Refine acceptor removal model work with DLs to Extended to cover temperature dependence of the bulk-damage related effects from room temperature down to -30 °C



# TRACS Development for LGAD

Ryuta Kiuchi

# TRACS Development for LGAD Sensors

- TRACS [1] is developed for a fast simulator tool of transient currents in silicon detectors
  - Ramo's theorem for calculating the transient current
  - FEniCS solver for Laplace/Poisson equations
  - Multi-threading
- Its lightweight and efficient implementation supports the fitting functionality to extract detector parameters
- Development has been started aiming for simulating LGAD sensors to deduce and compare parameters of LGADs both of non-irradiated and irradiated one.

[1] J. Calvo, P. de Castro, A. Díez González-Pardo, M. Fernández García, M. Moll, U. Senica, I. Vila, Nucl. Instrum. Meth. A 917 (2019) 77.

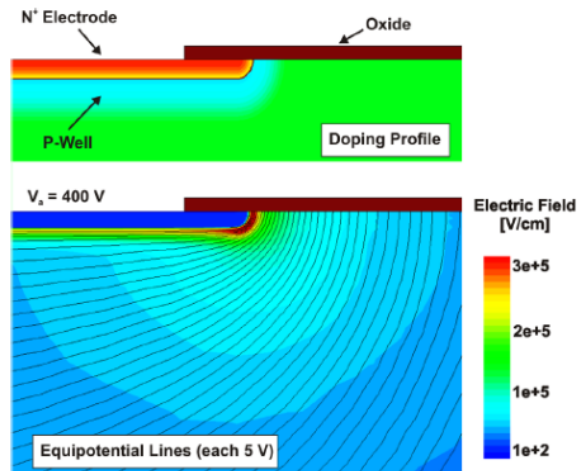
# Doping Profile

- Avalanche region in LGADs is reproduced
  - Neff parameters to set the effective doping profile
  - Simple Gaussian shape is assumed

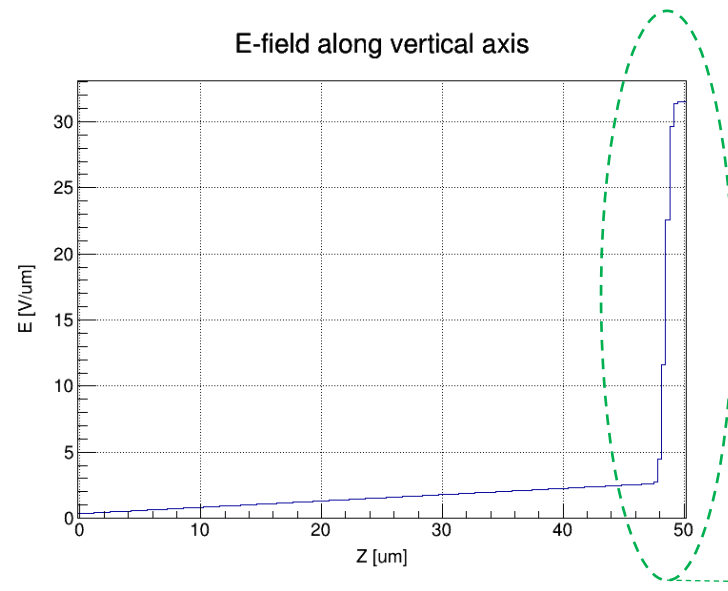
Doping profile set in the TRACS simulation



Doping profile deduced from CV measurements



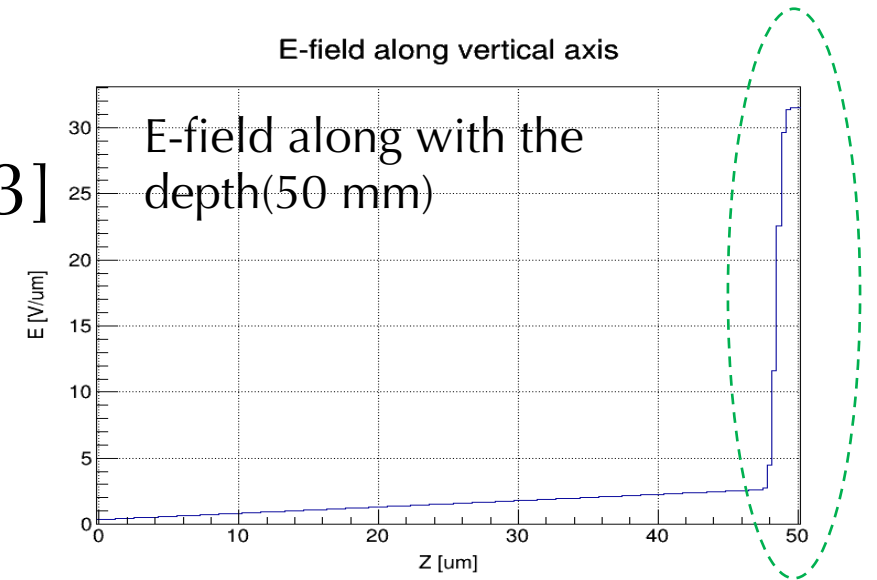
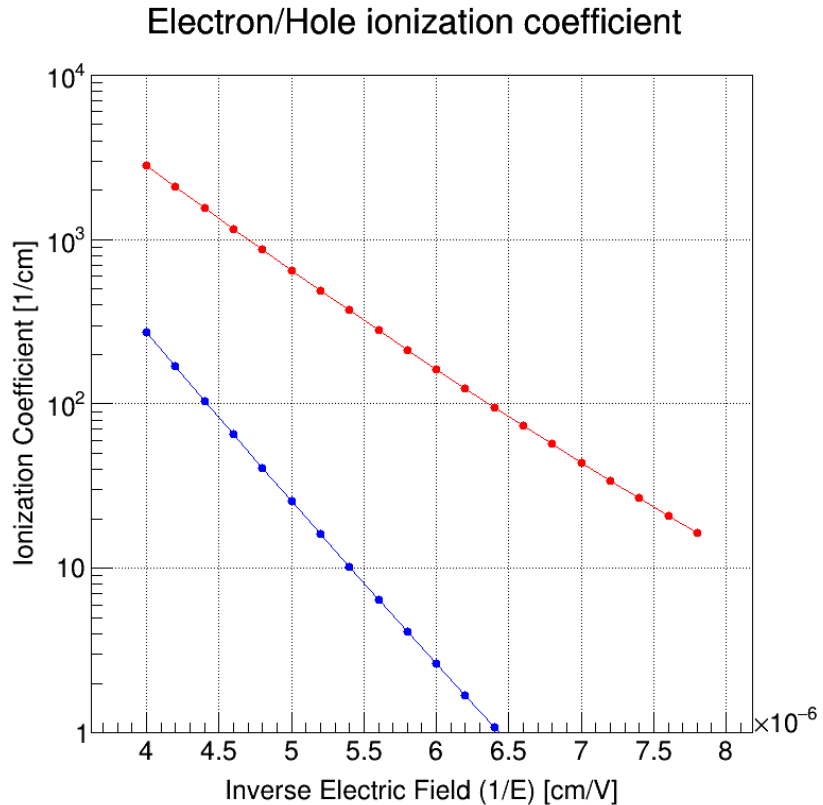
Schematic view of electric field and doping profile in LGAD [2]



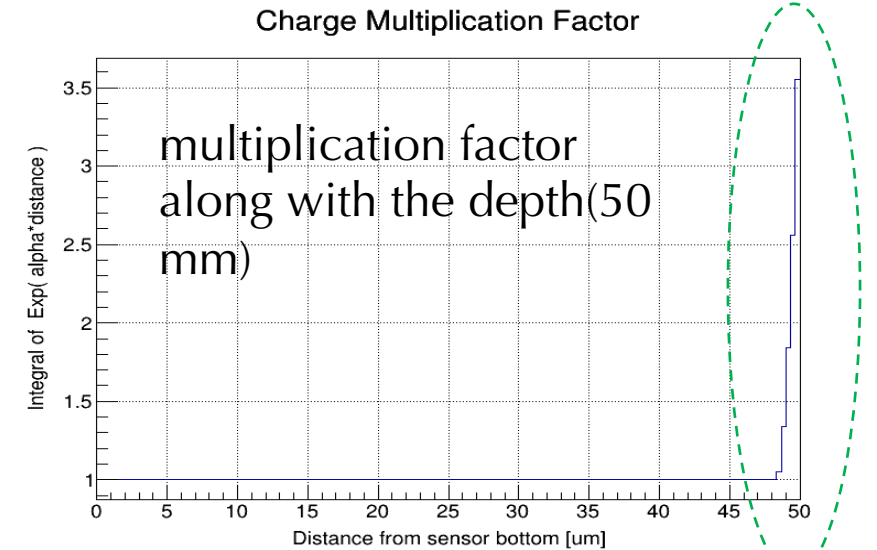
High electric field at “gain layer” in LGAD

# Impact Ionization Effect

- Adopt the impact ionization analytical model [3]

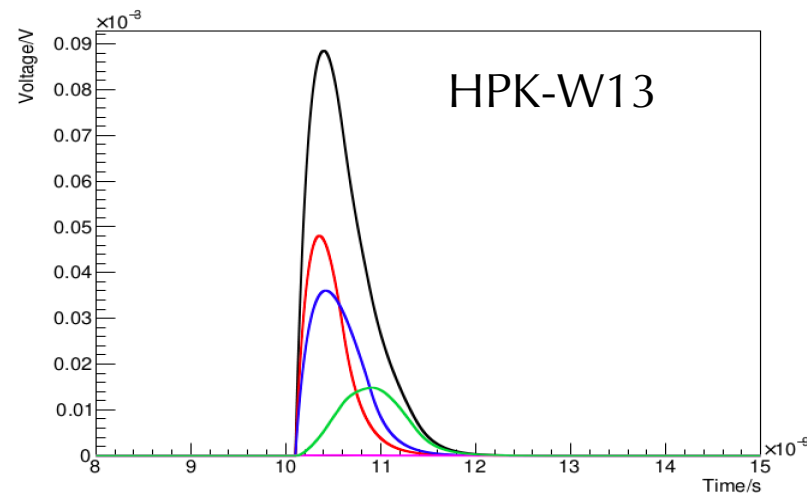
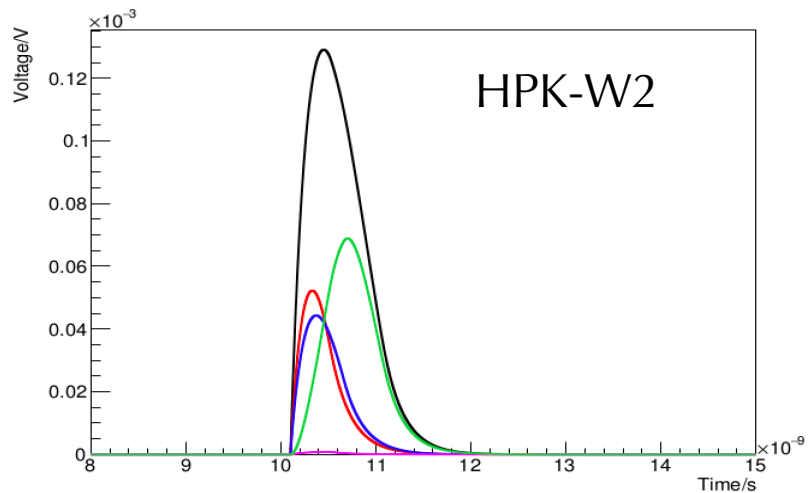
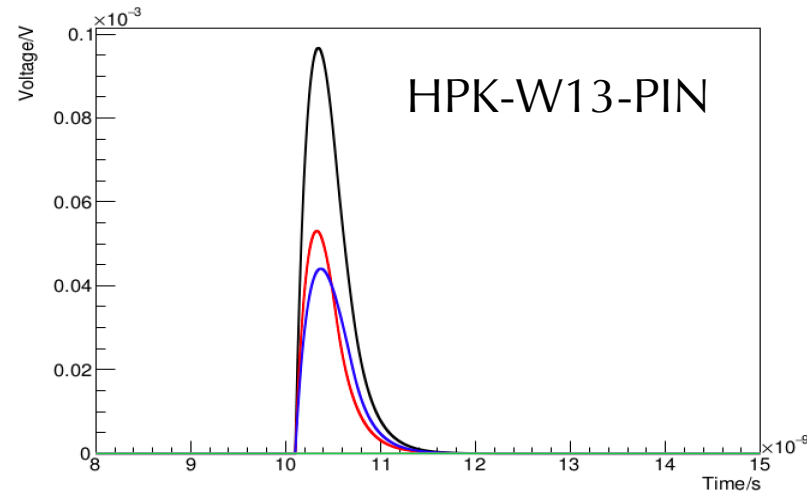
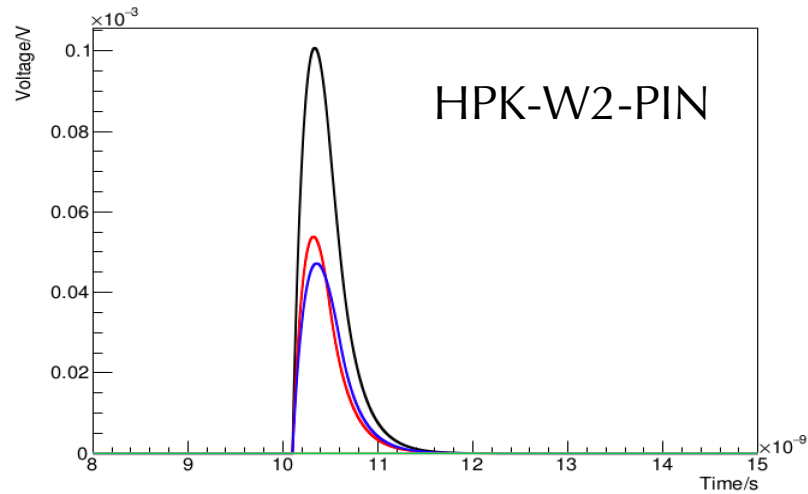


“gain layer” in LGAD



[3] M. Valdinoci, D. Ventura, M. C. Vecchi, M. Rudan, G. Baccarani, F. Illien, A. Stricker, L. Zullino, "Impact-ionization in silicon at large operating temperature", SISPAD '99, Sept. 6-8, 1999, Kyoto, Japan.

# Simulated Transient Current



Upper panels: PIN sensor  
(=wo Gain layer)

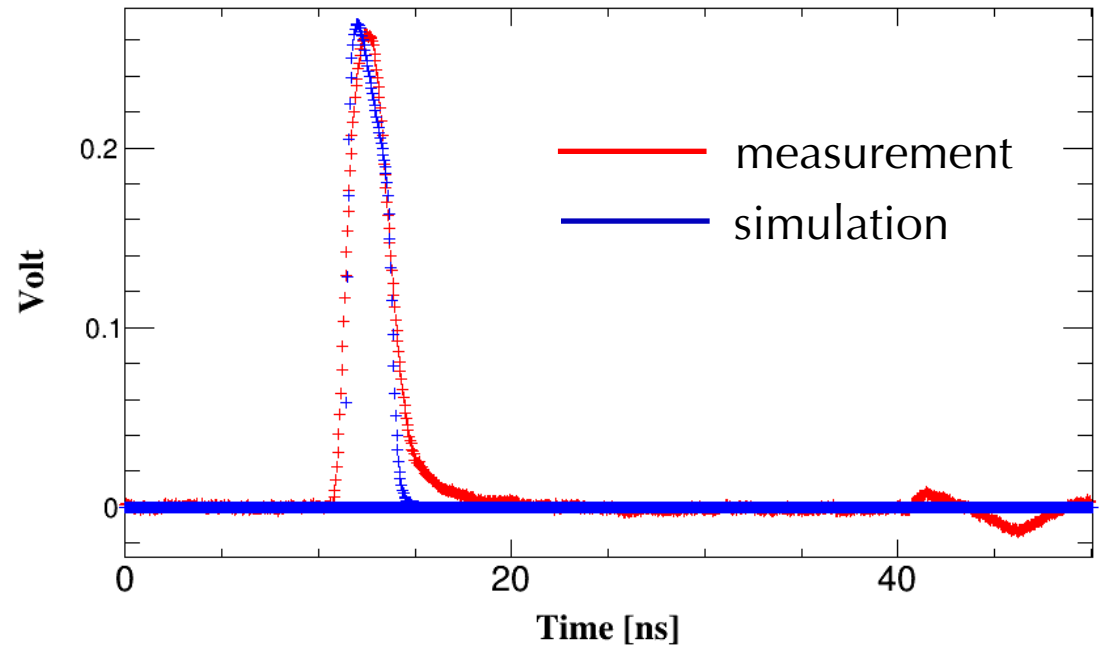
Lower panels : LGAD sensor  
(= w Gain layer)

- Total current
- Initial electron current
- Initial hole current
- Generated electron current
- Generated hole current

*IR-Top configuration*

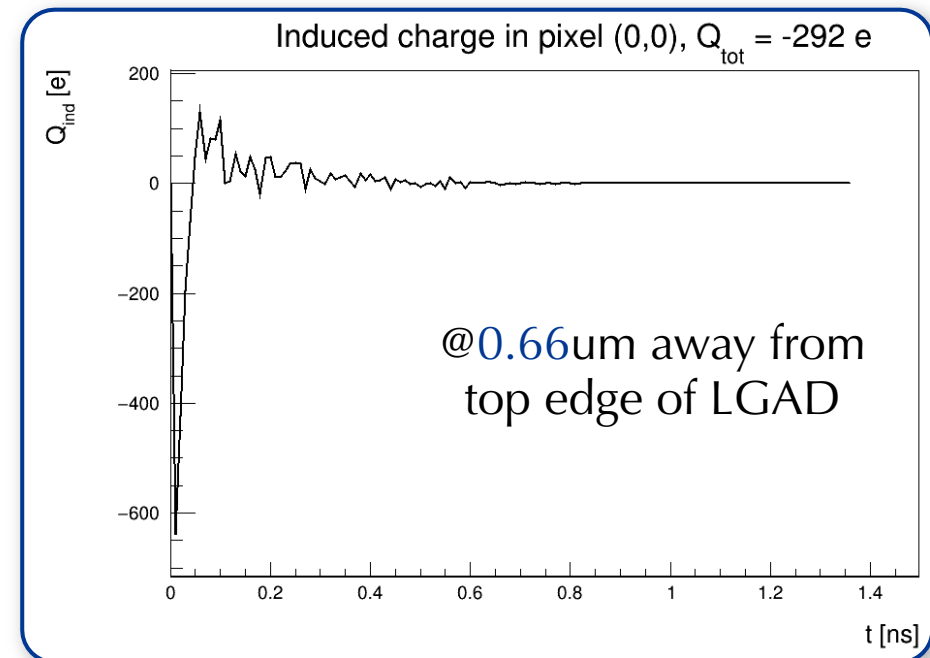
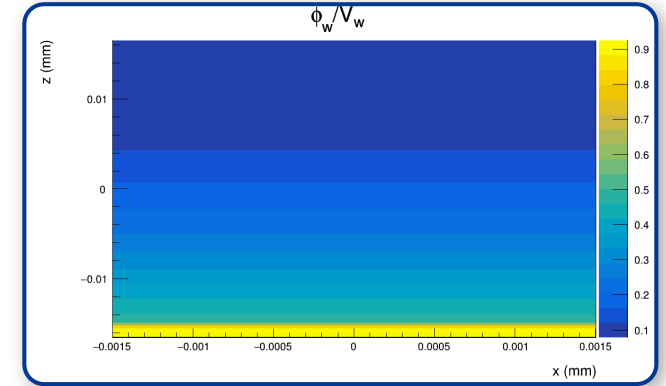
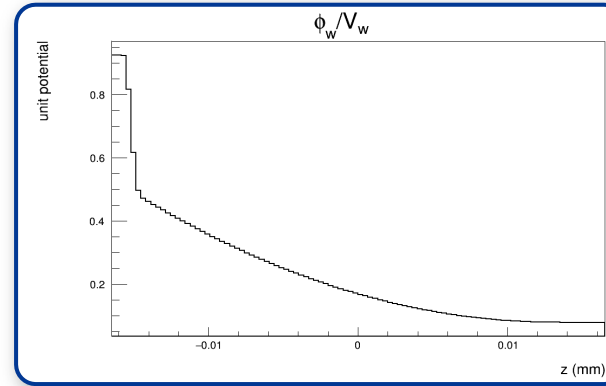
# Status

- Comparison with the measurement has been just began
  - Right figure shows an example of HPK W13 LGAD , Red-Top TCT
  - May need to tune the response function ?
  - Need further investigations
- What's next ?
  - Simulate the irradiated sensors
  - ...
  - Any suggestions/comments are highly appreciated !



# Allpix2 simulation

- LGAD
  - Size:  $2\mu\text{m} * 1.04\text{mm} * 33\mu\text{m}$
  - Material: Silicon
  - Support:
    - Size:  $2\mu\text{m} * 1.04\text{mm}$
    - Thickness:  $30\mu\text{m}$
    - Material: Aluminium
- Source
  - Particle: gamma
  - Energy:  $5.4\text{keV}$
- Weighting potential field
  - 2D:  $x z$  plane
  - Volt:  $-50\text{V}$



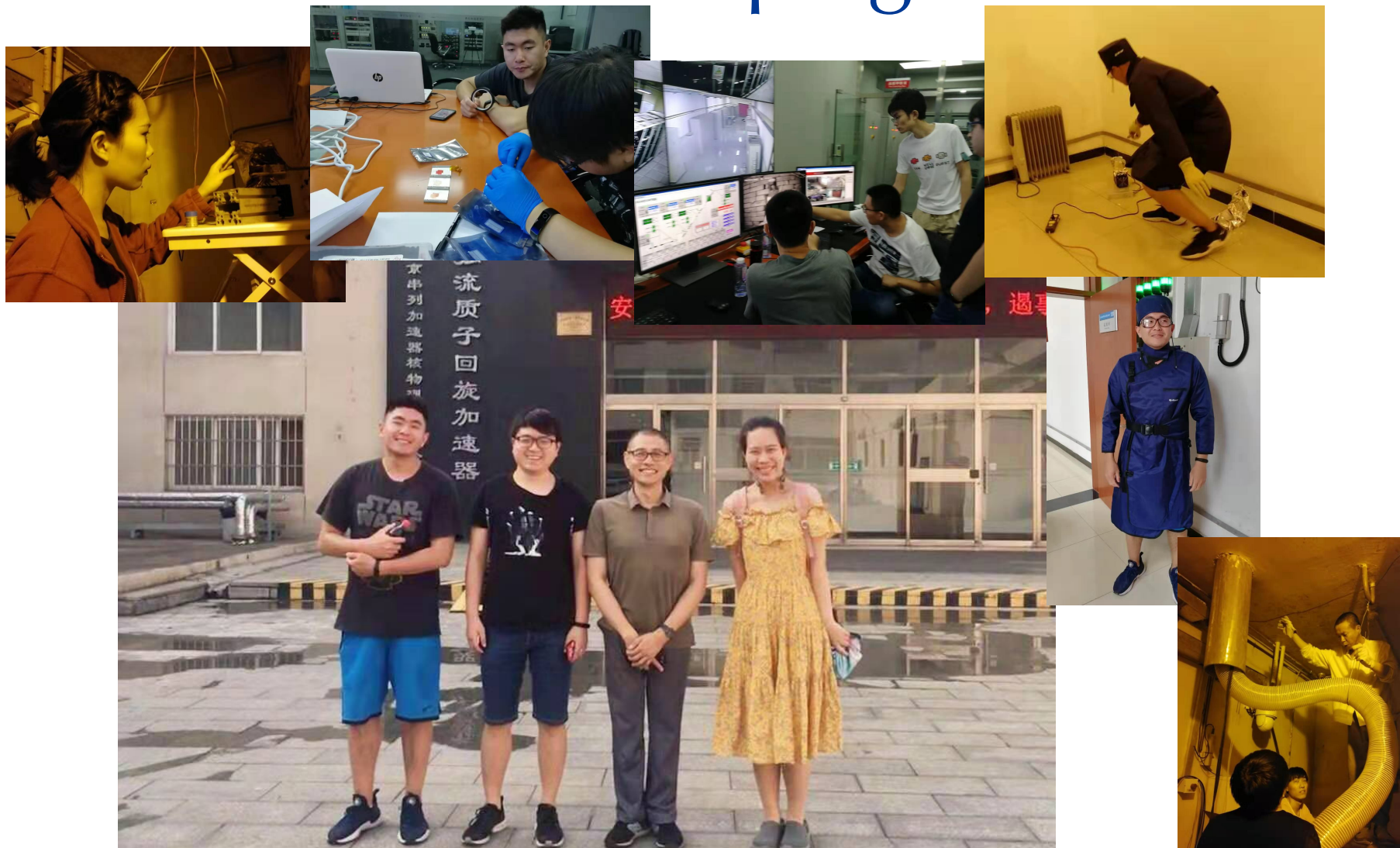
# Summary

- There batches of LGAD sensor has been made in China with promising test results, including IV, CV, TCT, Beta sources.
- The first proton irradiation at CIAE has been done successfully with on-going tests and TCAD irradiation modeling
- TRACS with LGAD feature has been implemented along with Allpix2 investigation.

Stay tuned for more RD50 related activities from IHEP !



# CIAE Irradiation Campaign – Thanks all!



Kewei Yuhang XS Suyu